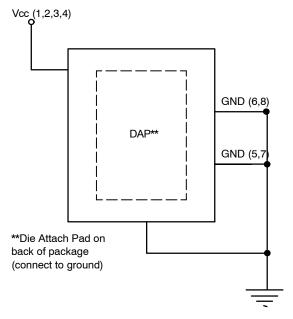
NSPU5132

13.5 V Unidirectional ESD and Surge Protection Device

Features

- Unidirectional High Voltage ESD & Surge Protection Device
- Provides ESD Protection to IEC61000-4-2 Level 4: ±30 kV Contact Discharge
- Small Package (1.8 mm x 2.0 mm)
- High Voltage Zener Diode Protects Supply Rail up to 200 A (8/20 μs)
- These Devices are Pb-Free and are RoHS Compliant

APPLICATION DIAGRAM





ON Semiconductor®

www.onsemi.com



UDFN6 D4 SUFFIX CASE 517CS

BLOCK DIAGRAM



MARKING DIAGRAM



4W = Specific Device Code

M = Date Code

= Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
NSPU5132MUTBG	UDFN6	3000 / Tape &
	(Pb-Free)	Reel

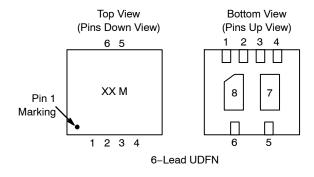
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NSPU5132

Table 1. PIN DESCRIPTIONS

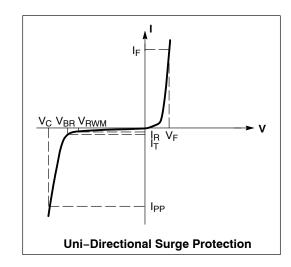
6-Lead, UDFN-8 Package						
Pin	Name	Description				
1	V _{CC}	Cathode				
2	V _{CC}	Cathode				
3	V _{CC}	Cathode				
4	V _{CC}	Cathode				
5	GND	Anode				
6	GND	Anode				
7	GND	Anode				
8	GND	Anode				

PACKAGE / PINOUT DIAGRAMS



ELECTRICAL CHARACTERISTICS

Symbol	Parameter				
I _{PP}	Maximum Reverse Peak Pulse Current				
V _C	Clamping Voltage @ I _{PP}				
V _{RWM}	Working Peak Reverse Voltage				
I _R	Maximum Reverse Leakage Current @ V _{RWM}				
V _{BR}	Breakdown Voltage @ I _T				
I _T	Test Current				
ΘV _{BR}	Maximum Temperature Coefficient of V _{BR}				
IF	Forward Current				
V _F	Forward Voltage @ I _F				



SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Units
Operating Temperature Range	-55 to +125	°C
Storage Temperature Range	−65 to +150	°C
Peak Current (t _p = 8/20 μs)	200	Α
Peak Pulse Power (t _p = 8/20 μs)	4800	W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ELECTRICAL CHARACTERISTICS

		V _{RWM} (V)	I _R @ V _{RWM}	Breakdown Voltage			V _C @ (8 x 20 μs		Junction C (V _R = 0 V, Pin 1 to	f = 1 MHz,	
Device	Device	(Note 1)	(μ A)	V _B	V _{BR} V (Note 2) @ I _T (m/		@ I _T (mA)	V _C (V)	I _{PP} (A)	C ^J ((pF)
Name	Marking	Max	Max	Min	Nom	Max		Max		Тур	Max
NSPU5132	4W	13.5	0.5	13.6	15.5	17.5	1	24	200	1325	1550

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- A surge protector is normally selected according to the working peak reverse voltage (V_{RWM}), which should be equal to or greater than the DC or continuous peak operating voltage level.
- 2. V_{BR} measured at pulse test current I_T at an ambient temperature of 25°C.
- 3. Surge current waveform per Figure 1.

NSPU5132

TYPICAL CHARACTERISTICS

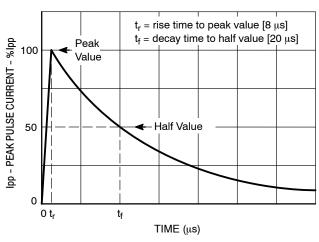


Figure 1. IEC61000-4-5 8/20 μs Pulse Waveform

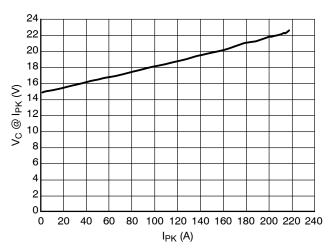


Figure 2. Positive Clamping Voltage vs. Peak Pulse Current

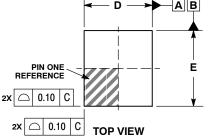


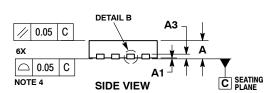


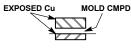
UDFN6, 1.8x2, 0.4P CASE 517CS ISSUE O

DATE 30 APR 2013

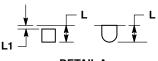
D AB PIN ONE REFERENCE 0.10 C







DETAIL B ALTERNATE CONSTRUCTION



DETAIL A ALTERNATE CONSTRUCTIONS

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION & APPLIES TO PLATED TERMINALS
 AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
 COPLANARITY APPLIES TO THE EXPOSED PAD
- AS WELL AS THE TERMINALS.

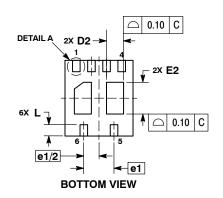
	MILLIMETERS					
DIM	MIN	MAX				
Α	0.45	0.55				
A1	0.00	0.05				
A3	0.125 REF					
b	0.15 0.25					
D	1.80 BSC					
D2	0.35	0.55				
E	2.00 BSC					
E2	0.74 0.94					
е	0.40 BSC					
e1	0.80 BSC					
e2	0.95 BSC					
L	0.20	0.40				
L1		0.15				

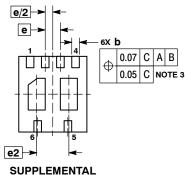
GENERIC MARKING DIAGRAM*



XX = Specific Device Code Μ = Date Code

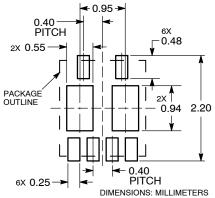
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.





BOTTOM VIEW

RECOMMENDED MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON89602E	Electronic versions are uncontrolled except when accessed directly from the Document Reposite Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	UDFN6 1.8X2, 0.4P		PAGE 1 OF 1		

onsemi and Onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries, onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales